



# Rayson eMMC 5.1 Datasheet

**RS70B08G3S03F**

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Version 1.4

**RAYSON ELECTRONICS LIMITED**

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## Revision History

| Version | Date       | Editor | History                        |
|---------|------------|--------|--------------------------------|
| V1.0    | 2021-9-6   |        | Initial release.               |
| V1.1    | 2021-12-20 |        | Update PNM and fix typo error. |
| V1.3    | 2022-01-07 |        | Modify CID/Temp                |
| V1.4    | 2023-04-01 |        | Modify Cmdq depth              |
|         |            |        |                                |

*This data sheet contains minimum and maximum limits specified over the power supply and temperature range set forth herein. Although considered final, these specifications are subject to change at any time without notice, as further product development and data characterization sometimes occur.*

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# 1. Product Overview

## 1.1. Introduction

Rayson eMMC product is a high quality and cost advantage embedded storage solution and compatible with JEDEC standard eMMC5.1 specification. Its strong ECC engine significantly improves error correction enabling longer device lifetime and an increased ability to handle higher raw bit error rate.

The Rayson eMMC product consists of NAND flash and an eMMC controller. The eMMC controller and software directly manage NAND flash, including ECC, wear-leveling, bad block management, garbage collection and performance optimization, and manage interface protocols. This architecture insulates any revision of NAND flash from the eMMC Host, makes the eMMC device easy to integrate and accelerates time-to-market.

## 1.2. Feature Overview

eMMC feature overview:

- eMMC 5.1 specification compatibility
  - Backward compatible to eMMC 4.41/4.51/5.0
- Bus mode
  - Data bus width: 1 bit (default), 4 bits, 8 bits
  - Data transfer rate: up to 400MB/s (HS400)
  - Clock frequency: 0~200MHz
- Operating voltage range
  - $V_{CC}$ : 2.7 - 3.6V
  - $V_{CCQ}$ : 1.7 - 1.95V or 2.7 - 3.6V
- Support Hardware ECC engine
- Support auto power saving mode
- Preventing from sudden-power-off
- Support features defined in JEDEC standard
  - RPMB
  - Boot partition
  - Write protection
  - Erase, discard, trim, sanitize
  - HPI
  - Background operations
  - Device health report
  - Field firmware update(FFU)
  - Sleep / awake
  - Packed command
- Temperature range

| Part Number   | Operation    | Storage without Operation |
|---------------|--------------|---------------------------|
| RS70B08G3S03F | -25°C ~ 85°C | -40°C ~ 85°C              |

## 1.3. Product List

Table 1.3-1. Product List

| Density | Part Number   | NAND Flash Type | User Density (MB) | Package Size (mm) | Pin Configuration |
|---------|---------------|-----------------|-------------------|-------------------|-------------------|
| 8 GB    | RS70B08G3S03F | 64Gb x 1        | 7,400             | 11.5x13x0.92      | 153 TFBGA         |

# 2. Product Specification

## 2.1. Partition Size

### 2.1.1. Factory Configuration

The device initially consists of two Boot Partitions, RPMB Partition and User Data Area. Both Boot and RPMB area have fixed size of area and can not be adjusted.

Table 2.1-1. Partition Size

| Density | Boot Partition 1 (KB) | Boot Partition 2 (KB) | RPMB (KB) | User Data Area |           |
|---------|-----------------------|-----------------------|-----------|----------------|-----------|
|         |                       |                       |           | Percent        | Size (MB) |
| 8 GB    | 4096                  | 4096                  | 4096      | 90%            | 7,400     |

### 2.1.2. Partition Management

The User Data Area can be divided into four General Purpose Area Partitions and User Data Area partition with independent address spaces, starting from logical address 0x00000000. Each of the General Purpose Area Partitions and a section of User Data Area partition can be configured as enhanced partition. These partition management operations are one-time programmable.

The enhanced partitions are true SLC mode partition. When customer set some portion as enhanced partitions in User Data Area, these partitions occupy double(MLC)/triple(TLC) size of the original set-up size. If set 1MB for enhanced mode, total 2MB(MLC)/3MB(TLC) user data area is needed to generate 1MB enhanced area.

Table 2.1-2. Max Enhanced Partition Size

| Density | Max. Enhanced Partition Size (MB) |
|---------|-----------------------------------|
| 8 GB    | 3696                              |

## 2.2. Power Consumption

### 2.2.1. Standby State

Table 2.2-1. Power consumption in auto power saving mode and standby state

| Density | I <sub>CCQ</sub> (uA) |      | I <sub>CC</sub> (uA) |      |
|---------|-----------------------|------|----------------------|------|
|         | 25°C(Typ.)            | 85°C | 25°C(Typ.)           | 85°C |
| 8 GB    | 100                   | 550  | 70                   | 150  |

#### Note:

1. The measurement for max RMS current is the average RMS current consumption over a period of 100ms.
2. In Standby Power mode, V<sub>CCQ</sub> & V<sub>CC</sub> power supply is switched on. No data transaction period before entering sleep status, no clock. V<sub>CCQ</sub> = 1.8V & V<sub>CC</sub> = 3.3V. Not 100% tested.

## 2.2.2. Sleep State

Table 2.2-2. Power consumption in sleep state

| Density | I <sub>CCQ</sub> (uA) |      | I <sub>CC</sub> (uA) |
|---------|-----------------------|------|----------------------|
|         | 25°C(Typ.)            | 85°C |                      |
| 8 GB    | 100                   | 550  | 0                    |

### Note:

1. The measurement for max RMS current is the average RMS current consumption over a period of 100ms.
2. In Sleep state, triggered by CMD5, V<sub>CC</sub> power supply is switched off (V<sub>CCQ</sub> on). V<sub>CCQ</sub> = 1.8V & V<sub>CC</sub> = 0V. Not 100% tested.
3. In auto power saving mode, NAND power V<sub>CC</sub> can not be switched off. However in sleep mode V<sub>CC</sub> can be switched off. If NAND power V<sub>CC</sub> is alive, it is same with that of the Standby state.

## 2.2.3. Active State

Table 2.2-3. Power consumption in active state

| Mode  | Operation | Item             | Power Consumption Value | Units |
|-------|-----------|------------------|-------------------------|-------|
|       |           |                  | 8 GB                    |       |
| HS400 | Read      | I <sub>CC</sub>  | 50                      | mA    |
|       |           | I <sub>CCQ</sub> | 30                      | mA    |
|       | Write     | I <sub>CC</sub>  | 60                      | mA    |
|       |           | I <sub>CCQ</sub> | 26                      | mA    |
| HS200 | Read      | I <sub>CC</sub>  | 50                      | mA    |
|       |           | I <sub>CCQ</sub> | 28                      | mA    |
|       | Write     | I <sub>CC</sub>  | 60                      | mA    |
|       |           | I <sub>CCQ</sub> | 24                      | mA    |
| DDR52 | Read      | I <sub>CC</sub>  | 48                      | mA    |
|       |           | I <sub>CCQ</sub> | 26                      | mA    |
|       | Write     | I <sub>CC</sub>  | 57                      | mA    |
|       |           | I <sub>CCQ</sub> | 22                      | mA    |

### Note:

1. The measurement for max RMS current is the average RMS current consumption over a period of 100ms.
2. V<sub>CCQ</sub> = 1.8V & V<sub>CC</sub> = 3.3V.

## 2.3. Performance

Table 2.3-1. Performance value at the initial stage.

| Mode  | Item             | Performance Value | Units |
|-------|------------------|-------------------|-------|
|       |                  | 8 GB              |       |
| HS400 | Sequential Write | 110               | MB/s  |
|       | Sequential Read  | 160               | MB/s  |
| HS200 | Sequential Write | 110               | MB/s  |
|       | Sequential Read  | 158               | MB/s  |
| DDR52 | Sequential Write | 67                | MB/s  |
|       | Sequential Read  | 82                | MB/s  |

### Note:

1. Measured on internal board, 512KB data transfer, cache on, without file system overhead.

2. Device will exit initial stage and never return to the initial stage again, when the accumulated data size written into different LBAs is greater than the half of device capacity.

Table 2.3-2. Performance value after exit initial stage.

| Mode  | Item             | Performance Value | Units |
|-------|------------------|-------------------|-------|
|       |                  | 8 GB              |       |
| HS400 | Sequential Write | 31                | MB/s  |
|       | Sequential Read  | 150               | MB/s  |
| HS200 | Sequential Write | 30                | MB/s  |
|       | Sequential Read  | 140               | MB/s  |
| DDR52 | Sequential Write | 30                | MB/s  |
|       | Sequential Read  | 80                | MB/s  |

**Note:**

1. Measured on internal board, 512KB data transfer, cache on, without file system overhead.

## 3. Pin and Package

### 3.1. Signal Definition and Ball Map

Table 3.1-1. Ball & Signal Assignment

| Ball No. | Signal          | Type | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               |
|----------|-----------------|------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| A3       | DAT0            | I/O  | Data I/O: These are bidirectional data signals. The DAT signals operate in push-pull mode. By default, after power-on or assertion of the RST_n signal, only DAT0 is used for data transfer. The MMC controller can configure a wider data bus for data transfer either using DAT[3:0] (4-bit mode) or DAT[7:0] (8-bit mode). eMMC includes internal pull-up resistors for data lines DAT[7:1]. Immediately after entering the 4-bit mode, the device disconnects the internal pull-up resistors on the DAT[3:1] lines. Upon entering the 8-bit mode, the device disconnects the internal pull-ups on the DAT[7:1] lines. |
| A4       | DAT1            | I/O  |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| A5       | DAT2            | I/O  |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| B2       | DAT3            | I/O  |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| B3       | DAT4            | I/O  |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| B4       | DAT5            | I/O  |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| B5       | DAT6            | I/O  |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| B6       | DAT7            | I/O  |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| M5       | CMD             | I/O  | Command: This signal is a bidirectional command channel used for command and response transfers. The CMD signal has two bus modes: open-drain mode and push-pull mode. Commands are sent from the MMC host to the device, and responses are sent from the device to the host.                                                                                                                                                                                                                                                                                                                                             |
| M6       | CLK             | I    | Clock: Each cycle of the clock directs a transfer on the command line and on the data line(s). The frequency can vary between the minimum and the maximum clock frequency.                                                                                                                                                                                                                                                                                                                                                                                                                                                |
| K5       | RST_n           | I    | Reset: The RST_n signal is used by the host for resetting the device, moving the device to the pre-idle state. By default, the RST_n signal is temporarily disabled in the device. The host must set EXT_CSD register byte 162, bits[1:0] to 0x1 to enable this functionality before the host can use it.                                                                                                                                                                                                                                                                                                                 |
| H5       | DS              | O    | Data strobe: Generated by the device and used for data output and CRC status response output in HS400 mode. The frequency of this signal follows the frequency of CLK. For data output, each cycle of this signal directs two bits transfer (2x) on the data, one bit for the positive edge and the other bit for the negative edge. For CRC status response output, the CRC status is latched on the positive edge only, and is "Don't Care" on the negative edge.                                                                                                                                                       |
| E6       | V <sub>CC</sub> | P    | VCC: NAND interface I/O and NAND Flash power supply                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                       |

| Ball No. | Signal           | Type | Description                                                |
|----------|------------------|------|------------------------------------------------------------|
| F5       | V <sub>CC</sub>  | P    |                                                            |
| J10      | V <sub>CC</sub>  | P    |                                                            |
| K9       | V <sub>CC</sub>  | P    |                                                            |
| C6       | V <sub>CCQ</sub> | P    | VCCQ: eMMC controller core and eMMC I/F I/O power supply.  |
| M4       | V <sub>CCQ</sub> | P    |                                                            |
| N4       | V <sub>CCQ</sub> | P    |                                                            |
| P3       | V <sub>CCQ</sub> | P    |                                                            |
| P5       | V <sub>CCQ</sub> | P    |                                                            |
| E7       | V <sub>SS</sub>  | P    | VSS: NAND interface I/O and NAND Flash ground connection.  |
| G5       | V <sub>SS</sub>  | P    |                                                            |
| H10      | V <sub>SS</sub>  | P    |                                                            |
| K8       | V <sub>SS</sub>  | P    |                                                            |
| A6       | V <sub>SS</sub>  | P    |                                                            |
| J5       | V <sub>SS</sub>  | P    |                                                            |
| C4       | V <sub>SSQ</sub> | P    | VSSQ: eMMC controller core and eMMC I/F ground connection. |
| N2       | V <sub>SSQ</sub> | P    |                                                            |
| N5       | V <sub>SSQ</sub> | P    |                                                            |
| P4       | V <sub>SSQ</sub> | P    |                                                            |
| P6       | V <sub>SSQ</sub> | P    |                                                            |
| C2       | V <sub>DDi</sub> | -    | Internal voltage node.                                     |

**Note:**

- (1) I/O = Bi-direction, I = Input, O = Output, P = Power/Analog
- (2) VSS and VSSQ are connected internally.

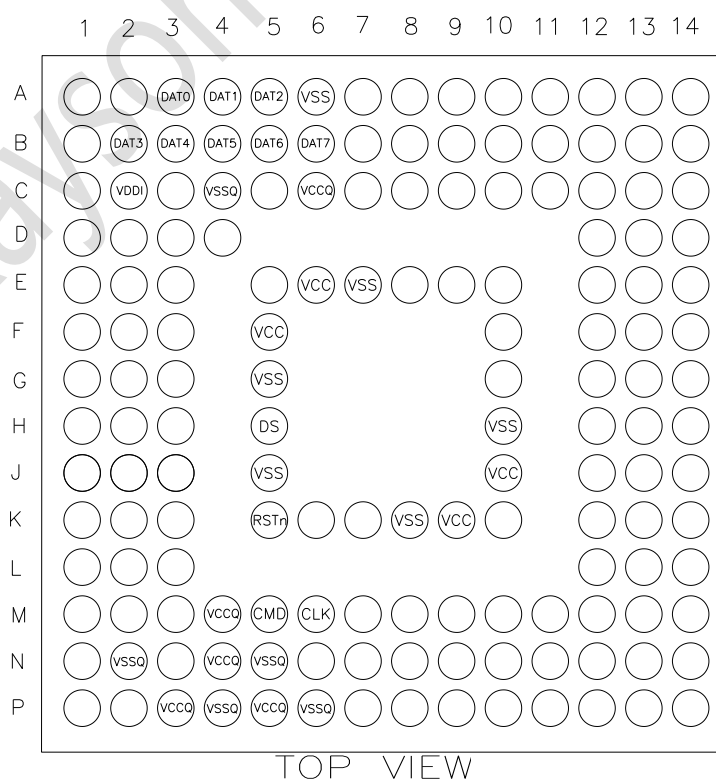


Figure 3.1-1. Ball Mapping

## 3.2. Package Dimension

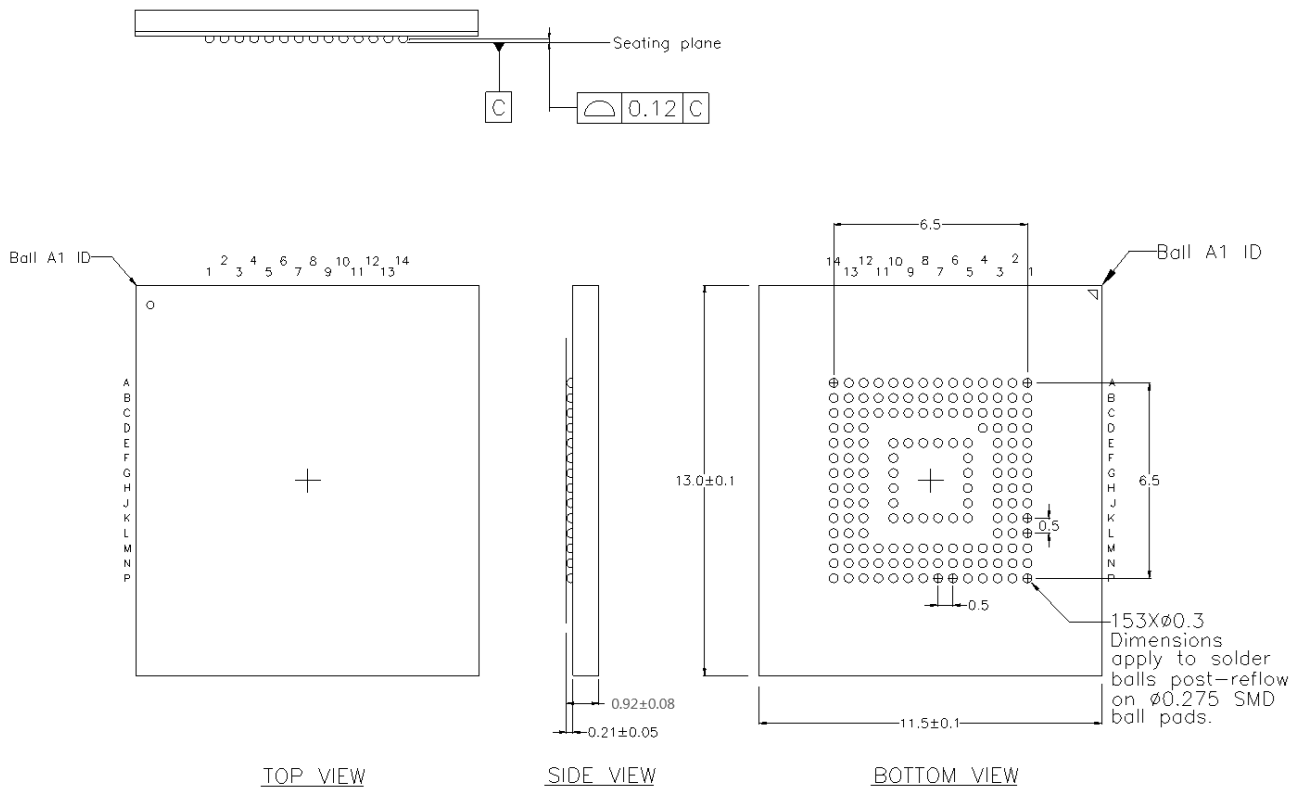


Figure 3.2-1. Package Dimension

## 4. Functional Description

### 4.1. Architecture and Application

The eMMC device consists of a single chip eMMC controller and NAND flash memory. The controller interfaces with a host system allowing data to be written to and read from the NAND flash memory, and handles flash management, including logical to physical translation, bad block management, wear leveling and so on. The interface is only 12-bit line, can support 1-bit/4-bit/8-bit data bus flexibly. Therefore, eMMC host can integrate the eMMC easily, access it like a MMC card, and do not care about NAND flash management.

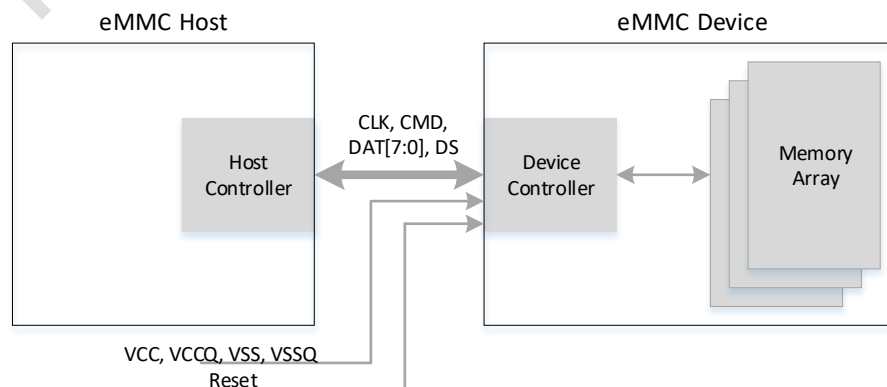


Figure 4.1-1. eMMC System Overview

## 4.2. Feature List

Table 4.2-1. Supported Feature List

| Ver. | Feature                                    | Benefit                                                                       | Support |
|------|--------------------------------------------|-------------------------------------------------------------------------------|---------|
| 4.41 | Background Operation                       | Better User Experience (low latency)                                          | Y       |
| 4.41 | Boot Partition and Operation               |                                                                               | Y       |
| 4.41 | Boot Partition Individual Write Protection |                                                                               | Y       |
| 4.41 | Partitioning & Protection                  | Flexibility                                                                   | Y       |
| 4.41 | Trim                                       |                                                                               | Y       |
| 4.41 | Secure Erase                               | True Wipe                                                                     | Y       |
| 4.41 | Secure TRIM                                | True Wipe                                                                     | Y       |
| 4.41 | RPMB                                       | Secure Folders                                                                | Y       |
| 4.41 | Write Reliability                          |                                                                               | Y       |
| 4.41 | Enhanced Reliable Write                    |                                                                               | Y       |
| 4.41 | Power Off Notification                     | Faster Boot; Responsiveness                                                   | Y       |
| 4.41 | HPI(High Priority Interrupt)               | Control Long Reads/Writes                                                     | Y       |
| 4.41 | HW Reset                                   | Robust System Design                                                          | Y       |
| 4.41 | Large Sector Size                          | Potential performance                                                         | N       |
| 4.5  | HS200                                      | Speed                                                                         | Y       |
| 4.5  | Extended Partition Attribute               | Flexibility                                                                   | Y       |
| 4.5  | Packed Command                             | Reduce Host Overhead                                                          | Y       |
| 4.5  | Discard                                    | Improved Performance on Full Media                                            | Y       |
| 4.5  | Data Tag                                   | Performance and/or Reliability                                                | Y       |
| 4.5  | Dynamic Capacity                           |                                                                               | Y       |
| 4.5  | Context Management                         | Performance and/or Reliability                                                | Y       |
| 4.5  | Real Time Clock info                       |                                                                               | Y       |
| 4.5  | Thermal Spec.                              |                                                                               | Y       |
| 4.5  | Cache                                      | Better Sequential & Random Writes                                             | Y       |
| 4.51 | Sanitize                                   | True Wipe                                                                     | Y       |
| 5.0  | HS400                                      | Speed                                                                         | Y       |
| 5.0  | Secure Removal Type                        |                                                                               | Y       |
| 5.0  | Device Health Report                       | Vital NAND info                                                               | Y       |
| 5.0  | Field Firmware Update                      |                                                                               | Y       |
| 5.0  | Production State Awareness                 | Different operation during production                                         | Y       |
| 5.0  | Sleep Notification                         |                                                                               | Y       |
| 5.1  | RPMB Throughput Improve                    | Faster RPMB write throughput                                                  | Y       |
| 5.1  | Secure Write Protection                    | Secure Write Protect                                                          | Y       |
| 5.1  | BKOPS Control                              | Host control on BKOPs                                                         | Y       |
| 5.1  | Command Queuing                            |                                                                               | N       |
| 5.1  | Enhanced Strobe                            | Sync Data out, CRC Response and CMD response between Device and Host in HS400 | Y       |

### 4.3. Boot Operation

Device supports both boot mode and alternative boot mode. Device supports high speed timing and dual data rate during boot mode.

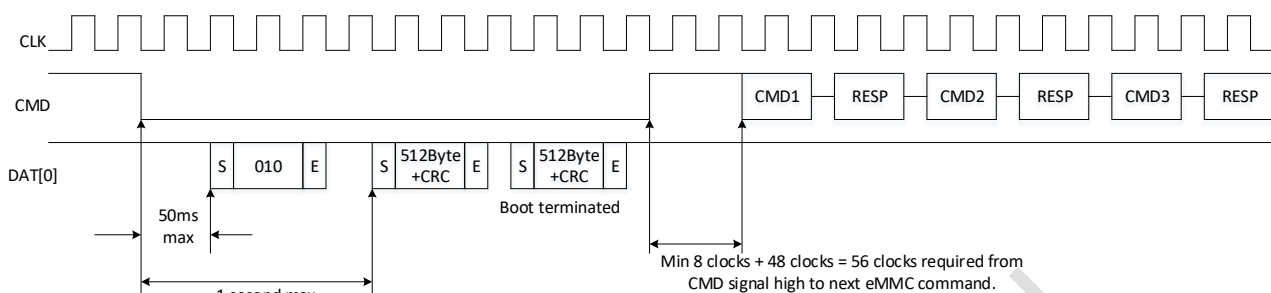


Figure 4.3-1. eMMC Boot Mode State Diagram

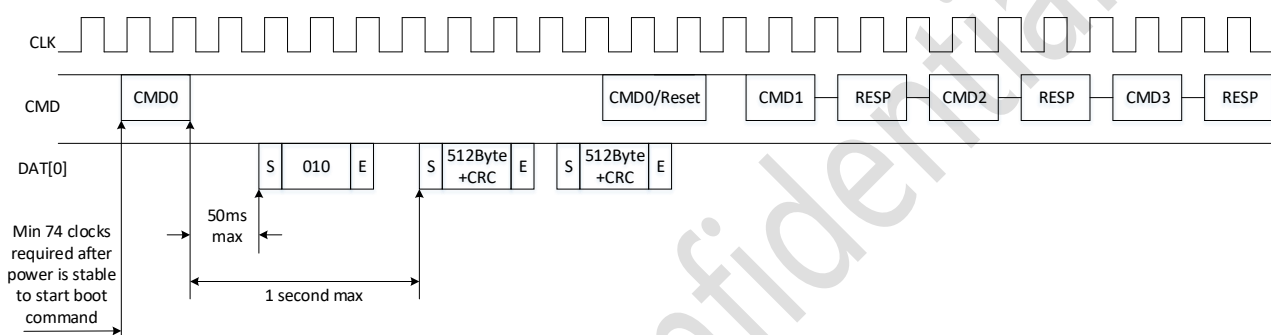


Figure 4.3-2. eMMC Alternative Boot Mode State Diagram

Table 4.3-1. Timing Parameter

| Timing Parameter        | Value   |
|-------------------------|---------|
| (1) Boot ACK Time       | < 50 ms |
| (2) Boot Data Time      | < 1 s   |
| (3) Initialization Time | < 1 s   |

### 4.4. H/W Reset Operation

H/W reset operation may be used to reset the device, moving the device to a Pre-idle state. For more information, refer to JESD84-B51 standard.

### 4.5. Device Health Report

Device supports Device Health Report feature which can provide an estimated indication about the device life time that is reflected by the averaged wear out of memory Type A and Type B. It can be queried by standard eMMC command for getting Extended CSD structure. Please refer to below and JEDEC Standards for details.

Table 4.5-1. Device Health Report

| Field                      | EXT_CSD Slice | Description                                                            |
|----------------------------|---------------|------------------------------------------------------------------------|
| DEVICE_LIFE_TIME_EST_TYP_A | 268           | Life time estimation of Type A(SLC) area.                              |
| DEVICE_LIFE_TIME_EST_TYP_B | 269           | Life time estimation of Type B(MLC/TLC) area.                          |
| PRE_EOL_INFO               | 267           | Indication about device life time reflected by average reserved blocks |

The device health feature will provide a % of the wear of the device in 10% fragments.

## 4.6. Field Firmware Update (FFU)

Device supports Field Firmware Updates (FFU) function to update firmware in field for those cases of debugging, enhancing and adding new features of firmware itself. The host can download a new version of the firmware into the eMMC device by this mechanism and whole FFU process can happen without affecting any user/OS data.

The Rayson eMMC only supports Manual mode (Mode\_OPERATION\_CODES is not supported). For more details, see as the following chart and register table given below.

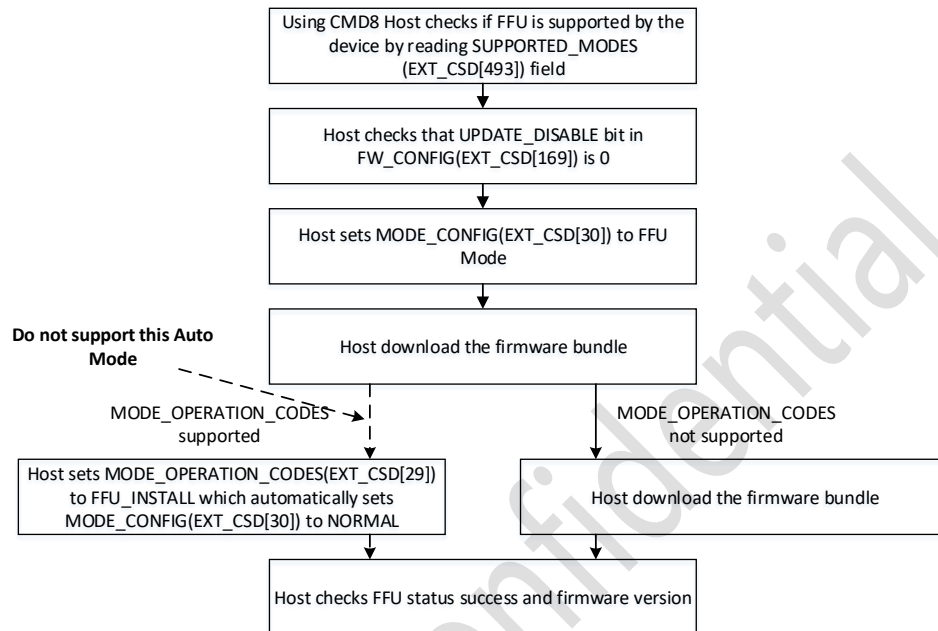


Figure 4.6-1. FFU Flow

The Rayson eMMC Field Firmware update command flow:

Table 4.6-1. FFU Flow

| Operation                             | Command                 | Note                                                                               |
|---------------------------------------|-------------------------|------------------------------------------------------------------------------------|
| Initialize device to transfer mode    | CMD0, ..., CMD7         |                                                                                    |
| Set bus width set frequency           |                         |                                                                                    |
| Set block length to 512B              | CMD16, Argu: 0x200      |                                                                                    |
| Get FFU argument                      | CMD8                    |                                                                                    |
| Enter FFU mode                        | CMD6, Argu: 0x031E0100  |                                                                                    |
| Send Firmware to device               | CMD25, Argu: FFU_ARGU   |                                                                                    |
| Stop data transfer                    | CMD12, Argu: 0x00000000 |                                                                                    |
| Exit FFU mode                         | CMD6, Argu: 0x031E0000  |                                                                                    |
| HW Reset/power cycle                  |                         |                                                                                    |
| Re-initialize device to transfer mode | CMD0, CMD1,...,CMD7     |                                                                                    |
| Check if FFU is succeeded             | CMD8, Argu: 0x00000000  | Check EXT_CSD[26], If FFU_SUCCESS is 0, FFU is succeeded, otherwise FFU is failed. |

### 4.6.1. EXT\_CSD Register for FFU

- SUPPORTED\_MODE[493] (Read Only)

Table 4.6-2. EXT\_CSD[493]

| Bit      | Field    | Supportability |
|----------|----------|----------------|
| Bit[7:2] | Reserved | -              |
| Bit[1]   | VSM      | Not support    |
| Bit[0]   | FFU      | Supported      |

BIT[0] :

- 0: FFU is not supported by the device.
- 1: FFU is supported by the device.

BIT[1] :

- 0: Vendor specific mode(VSM) is not supported by the device.
- 1: Vendor specific mode is supported by the device

## 2. FFU\_FEATURE[492] (Read Only)

Table 4.6-3. EXT\_CSD[492]

| Bit      | Field                          | Supportability |
|----------|--------------------------------|----------------|
| Bit[7:1] | Reserved                       | -              |
| Bit[0]   | SUPPORTED_MODE_OPERATION_CODES | Not support    |

BIT[0] :

- 0: Device does not support MODE\_OPERATION\_CODES field.
- 1: Device supports MODE\_OPERATION\_CODES field.

## 3. FFU\_ARG[490-487] (Read Only)

Using this field the device reports to the host which value the host should set as an argument for the read and write commands in FFU mode.

## 4. FFU\_CONFIG[169] (R/W)

Table 4.6-4. EXT\_CSD[169]

| Bit      | Field          | Supportability                 |
|----------|----------------|--------------------------------|
| Bit[7:1] | Reserved       | -                              |
| Bit[0]   | Update Disable | Firmware updates enabled (0x0) |

BIT[0] :

- 0: Enable update Firmware.
- 1: Disable update Firmware permanently.

## 5. FFU\_STATUS[26] (R/W/E\_P)

Using this field the device reports the status of the FFU process.

Table 4.6-5. EXT\_CSD[26]

| Value     | Description                   |
|-----------|-------------------------------|
| 0x00      | Success                       |
| 0x01-0x0F | Reserved                      |
| 0x10      | General Error                 |
| 0x11      | Firmware Install Error        |
| 0x12      | Error in Downloading Firmware |
| Others    | Reserved                      |

## 6. OPERATION\_CODES\_TIMEOUT[491](Read Only)

Maximum timeout for the SWITCH command when setting a value to the MODE\_OPERATION\_CODES field. The register is set to '0', because the device does not support MODE\_OPERATION\_CODES.

Table 4.6-6. EXT\_CSD[491]

| Value  | Description       |
|--------|-------------------|
| 0x00   | 0x0 (Not Defined) |
| Others | Reserved          |

#### 7. MODE\_OPERATION\_CODES[29] (W/E\_P)

The host sets the operation to be performed at the selected modes, in case MODE\_CONFIGS is set to FFU\_MODE, MODE\_OPERATION\_CODES could have the following values.

The Rayson device does not support MODE\_OPERATION\_CODES.

Table 4.6-7. EXT\_CSD[29]

| Value  | Description |
|--------|-------------|
| 0x00   | Reserved    |
| 0x01   | FFU_INSTALL |
| 0x02   | FFU_ABORT   |
| Others | Reserved    |

#### 8. MODE\_CONFIG [30] (R/W/E\_P)

Using this field the host can change the mode of the device

Table 4.6-8. EXT\_CSD[30]

| Value  | Description                             |
|--------|-----------------------------------------|
| 0x00   | Normal Mode (To keep the compatibility) |
| 0x01   | FFU Mode                                |
| 0x02   | Vendor Specific Mode                    |
| Others | Reserved                                |

## 4.7. Auto Power Saving Mode

If host does not issue any command during certain duration, the device will enters power saving mode to reduce power consumption. The host does not have to take any action for this to occur, however, in order to achieve the lowest sleep current, the host needs to shut down its clock to the memory device.

When the host is ready to access a device at any time, any command issued to device will cause it to exit sleep and respond immediately.

## 4.8. Sleep (CMD5)

The Device support using sleep/awake command (CMD5) to switch between a sleep and a standby state. In the sleep state the power consumption of the device is minimized and the device reacts only to the commands reset command (CMD0) and awake command (CMD5).

The VCC power supply support to be switched off in sleep state to minimize power consumption.

For more information, refer to JESD84-B51 standard.

# 5. Register Value

Within the device interface, six registers are defined: OCR, CID, CSD, EXT\_CSD, RCA and DSR. All of them can be accessed only corresponding commands. For detail information, please refer JESD84-B51 standard. The OCR, CID and CSD registers has information of device and content, while the RCA and DSR registers are for configuring parameters of device. For the EXT\_CSD register, it contains both device specific information and actual configuration parameters.

Following sections are for describing all register value of eMMC device at its default. And these values here may be updated in later version without notice.

## 5.1. OCR Register

The 32-bit operation conditions register (OCR) contains: VCC voltage profile of the device, access mode indication, status information bit. The status bit is set when the device finished its power up procedure.

Table 5.1-1. OCR Register

| OCR bit | V <sub>CCQ</sub> Voltage Window                                                                 | Register Value    |
|---------|-------------------------------------------------------------------------------------------------|-------------------|
| [6:0]   | Reserved                                                                                        | 000 0000b         |
| [7]     | 1.70 ~ 1.95                                                                                     | 1b                |
| [14:8]  | 2.0 ~ 2.6                                                                                       | 000 0000b         |
| [23:15] | 2.7 ~ 3.6                                                                                       | 1 1111 1111b      |
| [28:24] | Reserved                                                                                        | 0 0000b           |
| [30:29] | Access Mode                                                                                     | 10b (sector mode) |
| [31]    | eMMC power up status bit (busy).<br>This bit is set to LOW during the busy of power up routine. |                   |

## 5.2. CID Register

The card identification (CID) register is 128 bits wide. It contains the device identification information used during the card identification phase as required by eMMC protocol. Each device shall have a unique identification number.

Table 5.2-1. CID Register

| Name                  | Field | Width     | CID-slice | CID Value          |
|-----------------------|-------|-----------|-----------|--------------------|
| Manufacturer ID       | MID   | 8         | [127:120] | 0xEC               |
| Reserved              | 6     | [119:114] | ---       | 0x0                |
| Card/BGA              | CBX   | 2         | [113:112] | 0x01               |
| OEM/Application ID    | OID   | 8         | [111:104] | 0x00               |
| Product name          | PNM   | 48        | [103:56]  | 8GB: 0x41 54 32 53 |
| Product revision      | PRV   | 8         | [55:48]   | 0x10               |
| Product serial number | PSN   | 32        | [47:16]   | -                  |
| Manufacturing date    | MDT   | 8         | [15:8]    | -                  |
| CRC7 checksum         | CRC   | 7         | [7:1]     | -                  |
| not used, always '1'  | -     | 1         | [0:0]     | -                  |

## 5.3. CSD Register

The device Specific Data (CSD) register provides information on how to access the device contents. The CSD defines the data format, error correction type, maximum data access time, data transfer speed, whether the DSR register can be used etc. The programmable part of the register (entries marked by W or E) can be changed by CMD27.

For more information, refer to JESD84-B51 standard.

Table 5.3-1. CSD Register

| Name                                             | Field              | Width | Type  | CSD-slice | Value |
|--------------------------------------------------|--------------------|-------|-------|-----------|-------|
| CSD structure                                    | CSD_STRUCTURE      | 2     | R     | [127:126] | 0x03  |
| System specification version                     | SPEC_VERS          | 4     | R     | [125:122] | 0x04  |
| Reserved                                         | -                  | 2     | R     | [121:120] | 0x00  |
| Data read access-time 1                          | TAAC               | 8     | R     | [119:112] | 0x2F  |
| Data read access-time 2 in CLK cycles (NSAC*100) | NSAC               | 8     | R     | [111:104] | 0x01  |
| Max. bus clock frequency                         | TRAN_SPEED         | 8     | R     | [103:96]  | 0x32  |
| Device command classes                           | CCC                | 12    | R     | [95:84]   | 0x8F5 |
| Max. read data block length                      | READ_BL_LEN        | 4     | R     | [83:80]   | 0x09  |
| Partial blocks for read allowed                  | READ_BL_PARTIAL    | 1     | R     | [79:79]   | 0x00  |
| Write block misalignment                         | WRITE_BLK_MISALIGN | 1     | R     | [78:78]   | 0x00  |
| Read block misalignment                          | READ_BLK_MISALIGN  | 1     | R     | [77:77]   | 0x00  |
| DSR implemented                                  | DSR_IMP            | 1     | R     | [76:76]   | 0x00  |
| Reserved                                         | -                  | 2     | R     | [75:74]   | 0x00  |
| Device size                                      | C_SIZE             | 12    | R     | [73:62]   | 0xFFF |
| Max. read current @ VDD min                      | VDD_R_CURR_MIN     | 3     | R     | [61:59]   | 0x07  |
| Max. read current @ VDD max                      | VDD_R_CURR_MAX     | 3     | R     | [58:56]   | 0x07  |
| Max. write current @ VDD min                     | VDD_W_CURR_MIN     | 3     | R     | [55:53]   | 0x07  |
| Max. write current @ VDD max                     | VDD_W_CURR_MAX     | 3     | R     | [52:50]   | 0x07  |
| Device size multiplier                           | C_SIZE_MULT        | 3     | R     | [49:47]   | 0x07  |
| Erase group size                                 | ERASE_GRP_SIZE     | 5     | R     | [46:42]   | 0x1F  |
| Erase group size multiplier                      | ERASE_GRP_MULT     | 5     | R     | [41:37]   | 0x1F  |
| Write protect group size                         | WP_GRP_SIZE        | 5     | R     | [36:32]   | 0x0F  |
| Write protect group enable                       | WP_GRP_ENABLE      | 1     | R     | [31:31]   | 0x01  |
| Manufacturer default ECC                         | DEFAULT_ECC        | 2     | R     | [30:29]   | 0x00  |
| Write speed factor                               | R2W_FACTOR         | 3     | R     | [28:26]   | 0x03  |
| Max. write data block length                     | WRITE_BL_LEN       | 4     | R     | [25:22]   | 0x09  |
| Partial blocks for write allowed                 | WRITE_BL_PARTIAL   | 1     | R     | [21:21]   | 0x00  |
| Reserved                                         | -                  | 4     | R     | [20:17]   | 0x00  |
| Content protection application                   | CONTENT_PROT_APP   | 1     | R     | [16:16]   | 0x00  |
| File format group                                | FILE_FORMAT_GRP    | 1     | R/W   | [15:15]   | 0x00  |
| Copy flag (OTP)                                  | COPY               | 1     | R/W   | [14:14]   | 0x00  |
| Permanent write protection                       | PERM_WRITE_PROTECT | 1     | R/W   | [13:13]   | 0x00  |
| Temporary write protection                       | TMP_WRITE_PROTECT  | 1     | R/W/E | [12:12]   | 0x00  |
| File format                                      | FILE_FORMAT        | 2     | R/W   | [11:10]   | 0x00  |
| ECC code                                         | ECC                | 2     | R/W/E | [9:8]     | 0x00  |
| CRC                                              | CRC                | 7     | R/W/E | [7:1]     |       |
| Not used, always '1'                             | -                  | 1     | —     | [0:0]     |       |

Note:

1. Register type explanations:

(1) R = Read-only.

(2) R/W = One-time programmable and readable.

(3) R/W/E = Multiple writable with value kept after a power cycle, assertion of the RST\_n signal, and any CMD0 reset, and readable.

2. Reserved bits should be read as 0.

## 5.4. Extended CSD Register

Table 5.4-1. Extended CSD Register

| Name                                      | Field                                     | Size | Type | CSD-slice | Value          | Note |
|-------------------------------------------|-------------------------------------------|------|------|-----------|----------------|------|
| Reserved                                  | -                                         | 6    | TBD  | [511:506] | 0x00           |      |
| Extended Security Command Error           | EXT_SECURITY_ERR                          | 1    | R    | [505]     | 0x00           |      |
| Supported Command Set                     | S_CMD_SET                                 | 1    | R    | [504]     | 0x01           |      |
| HPI features                              | HPI_FEATURES                              | 1    | R    | [503]     | 0x01           |      |
| Background operation support              | BKOPS_SUPPORT                             | 1    | R    | [502]     | 0x01           |      |
| Max packed read commands                  | MAX_PACKED_READS                          | 1    | R    | [501]     | 0x3F           |      |
| Max packed write commands                 | MAX_PACKED_WRITES                         | 1    | R    | [500]     | 0x3F           |      |
| Data Tag Support                          | DATA_TAG_SUPPORT                          | 1    | R    | [499]     | 0x01           |      |
| Tag Unit Size                             | TAG_UNIT_SIZE                             | 1    | R    | [498]     | 0x00           |      |
| Tag Resource Size                         | TAG_RES_SIZE                              | 1    | R    | [497]     | 0x00           |      |
| Context management capabilities           | CONTEXT_CAPABILITIES                      | 1    | R    | [496]     | 0x05           |      |
| Large Unit size                           | LARGE_UNIT_SIZE_M1                        | 1    | R    | [495]     | 0x07           |      |
| Extended partitions attribute support     | EXT_SUPPORT                               | 1    | R    | [494]     | 0x03           |      |
| Supported modes                           | SUPPORTED_MODES                           | 1    | R    | [493]     | 0x01           |      |
| FFU features                              | FFU_FEATURES                              | 1    | R    | [492]     | 0x00           |      |
| Operation codes timeout                   | OPERATION_CODE_TIMEOUT                    | 1    | R    | [491]     | 0x00           |      |
| FFU Argument                              | FFU_ARG                                   | 4    | R    | [490:487] | 0xFFFF<br>FF5F |      |
| Barrier support                           | BARRIER_SUPPORT                           | 1    | R    | [486]     | 0x00           |      |
| Reserved                                  |                                           | 177  | TBD  | [485:309] | 0x00           |      |
| CMD Queuing Support                       | CMDQ_SUPPORT                              | 1    | R    | [308]     | 0x00           |      |
| CMD Queuing Depth                         | CMDQ_DEPTH                                | 1    | R    | [307]     | 0x00           |      |
| Reserved                                  |                                           | 1    |      | [306]     | 0x00           |      |
| Number of FW sectors correctly programmed | NUMBER_OF_FW_SECTORS_CORRECTLY_PROGRAMMED | 4    | R    | [305:302] | 0x00           |      |

| Name                                           | Field                            | Size | Type | CSD-slice | Value      | Note |
|------------------------------------------------|----------------------------------|------|------|-----------|------------|------|
| Vendor proprietary health report               | VENDOR_PROPRIETARY_HEALTH_REPORT | 32   | R    | [301:270] | 0x00       |      |
| Device life time estimation type B             | DEVICE_LIFE_TIME_EST_TYP_B       | 1    | R    | [269]     | 0x01       |      |
| Device life time estimation type A             | DEVICE_LIFE_TIME_EST_TYP_A       | 1    | R    | [268]     | 0x01       |      |
| Pre EOL information                            | PRE_EOL_INFO                     | 1    | R    | [267]     | 0x01       |      |
| Optimal read size                              | OPTIMAL_READ_SIZE                | 1    | R    | [266]     | 0x40       |      |
| Optimal write size                             | OPTIMAL_WRITE_SIZE               | 1    | R    | [265]     | 0x40       |      |
| Optimal trim unit size                         | OPTIMAL_TRIM_UNIT_SIZE           | 1    | R    | [264]     | 0x07       |      |
| Device version                                 | DEVICE_VERSION                   | 2    | R    | [263:262] | 0x203      |      |
| Firmware version                               | FIRMWARE_VERSION                 | 8    | R    | [261:254] | -          |      |
| Power class for 200MHz, DDR at VCC=3.6         | PWR_CL_DDR_200_360               | 1    | R    | [253]     | 0xDD       |      |
| Cache size                                     | CACHE_SIZE                       | 4    | R    | [252:249] | 0x00000400 |      |
| Generic CMD6 timeout                           | GENERIC_CMD6_TIME                | 1    | R    | [248]     | 0x64       |      |
| Power off notification (long) timeout          | POWER_OFF_LONG_TIME              | 1    | R    | [247]     | 0x8C       |      |
| Background operation status                    | BKOPS_STATUS                     | 1    | R    | [246]     | 0x00       |      |
| Number of correctly programmed sectors         | CORRECTLY_PRG_SECTORS_NUM        | 4    | R    | [245:242] | 0x00       |      |
| 1st initialization time after partitioning     | INI_TIMEOUT_AP                   | 1    | R    | [241]     | 0x0A       |      |
| Cache Flushing Policy                          | CACHE_FLUSH_POLICY               | 1    | R    | [240]     | 0x01       |      |
| Power class for 52MHz, DDR at VCC=3.6V         | PWR_CL_DDR_52_360                | 1    | R    | [239]     | 0xAA       |      |
| Power class for 52MHz, DDR at VCC=1.95V        | PWR_CL_DDR_52_195                | 1    | R    | [238]     | 0xDD       |      |
| Power class for 200MHz at VCCQ=1.95V, VCC=3.6V | PWR_CL_200_195                   | 1    | R    | [237]     | 0xDD       |      |
| Power class for 200MHz at VCCQ=1.3V, VCC=3.6V  | PWR_CL_200_130                   | 1    | R    | [236]     | 0xDD       |      |

| Name                                                    | Field                              | Size | Type | CSD-slice | Value      | Note |
|---------------------------------------------------------|------------------------------------|------|------|-----------|------------|------|
| Minimum Write Performance for 8bit at 52MHz in DDR mode | MIN_PERF_DDR_W_8_52                | 1    | R    | [235]     | 0x00       |      |
| Minimum Read Performance for 8bit at 52MHz in DDR mode  | MIN_PERF_DDR_R_8_52                | 1    | R    | [234]     | 0x00       |      |
| Reserved                                                |                                    | 1    | TBD  | [233]     | 0x00       |      |
| TRIM Multiplier                                         | TRIM_MULT                          | 1    | R    | [232]     | 0x16       |      |
| Secure Feature support                                  | SEC_FEATURE_SUPPORT                | 1    | R    | [231]     | 0x55       |      |
| Secure Erase Multiplier                                 | SEC_ERASE_MULT                     | 1    | R    | [230]     | 0x02       |      |
| Secure TRIM Multiplier                                  | SEC_TRIM_MULT                      | 1    | R    | [229]     | 0x02       |      |
| Boot information                                        | BOOT_INF                           | 1    | R    | [228]     | 0x07       |      |
| Reserved                                                |                                    | 1    | TBD  | [227]     | 0x00       |      |
| Boot partition size                                     | BOOT_SIZE_MULT                     | 1    | R    | [226]     | 0x20       |      |
| Access size                                             | ACC_SIZE                           | 1    | R    | [225]     | 0x07       |      |
| High-capacity erase unit size                           | HC_ERASE_GRP_SIZE                  | 1    | R    | [224]     | 0x01       |      |
| High-capacity erase timeout                             | ERASE_TIMEOUT_MULT                 | 1    | R    | [223]     | 0x16       |      |
| Reliable write sector count                             | REL_WR_SEC_C                       | 1    | R    | [222]     | 0x01       |      |
| High-capacity write protect group size                  | HC_WP_GRP_SIZE                     | 1    | R    | [221]     | 0x10       |      |
| Sleep current (Vcc)                                     | S_C_VCC                            | 1    | R    | [220]     | 0x08       |      |
| Sleep current (VccQ)                                    | S_C_VCCQ                           | 1    | R    | [219]     | 0x08       |      |
| Production state awareness timeout                      | PRODUCTION_STATE_AWARENESS_TIMEOUT | 1    | R    | [218]     | 0x0A       |      |
| Sleep/awake timeout                                     | S_A_TIMEOUT                        | 1    | R    | [217]     | 0x17       |      |
| Sleep Notification Timeout                              | SLEEP_NOTIFICATION_TIME            | 1    | R    | [216]     | 0x11       |      |
| Sector Count                                            | SEC_COUNT                          | 4    | R    | [215:212] | 0x00E74000 |      |
| Secure Write Protect Information                        | SECURE_WP_INFO                     | 1    | R    | [211]     | 0x01       |      |
| Minimum Write Performance for 8bit at 52MHz             | MIN_PERF_W_8_52                    | 1    | R    | [210]     | 0x0A       |      |

| Name                                                           | Field                 | Size | Type    | CSD-slice | Value | Note |
|----------------------------------------------------------------|-----------------------|------|---------|-----------|-------|------|
| Minimum Read Performance for 8bit at 52MHz                     | MIN_PERF_R_8_52       | 1    | R       | [209]     | 0x0A  |      |
| Minimum Write Performance for 8bit at 26MHz, for 4bit at 52MHz | MIN_PERF_W_8_26_4_52  | 1    | R       | [208]     | 0x0A  |      |
| Minimum Read Performance for 8bit at 26MHz, for 4bit at 52MHz  | MIN_PERF_R_8_26_4_52  | 1    | R       | [207]     | 0x0A  |      |
| Minimum Write Performance for 4bit at 26MHz                    | MIN_PERF_W_4_26       | 1    | R       | [206]     | 0x0A  |      |
| Minimum Read Performance for 4bit at 26MHz                     | MIN_PERF_R_4_26       | 1    | R       | [205]     | 0x0A  |      |
| Reserved                                                       |                       | 1    | TBD     | [204]     | 0x00  |      |
| Power class for 26MHz at 3.6V 1 R                              | PWR_CL_26_360         | 1    | R       | [203]     | 0x22  |      |
| Power class for 52MHz at 3.6V 1 R                              | PWR_CL_52_360         | 1    | R       | [202]     | 0xAA  |      |
| Power class for 26MHz at 1.95V 1 R                             | PWR_CL_26_195         | 1    | R       | [201]     | 0x22  |      |
| Power class for 52MHz at 1.95V 1 R                             | PWR_CL_52_195         | 1    | R       | [200]     | 0xAA  |      |
| Partition switching timing                                     | PARTITION_SWITCH_TIME | 1    | R       | [199]     | 0x32  |      |
| Out-of-interrupt busy timing                                   | OUT_OF_INTERRUPT_TIME | 1    | R       | [198]     | 0x0A  |      |
| I/O Driver Strength                                            | DRIVER_STRENGTH       | 1    | R       | [197]     | 0x1F  |      |
| Device type                                                    | DEVICE TYPE           | 1    | R       | [196]     | 0x57  |      |
| Reserved                                                       |                       | 1    | TBD     | [195]     | 0x00  |      |
| CSD STRUCTURE                                                  | CSD_STRUCTURE         | 1    | R       | [194]     | 0x02  |      |
| Reserved                                                       |                       | 1    | TBD     | [193]     | 0x00  |      |
| Extended CSD revision                                          | EXT_CSD_REV           | 1    | R       | [192]     | 0x08  |      |
| Command set                                                    | CMD_SET               | 1    | R/W/E_P | [191]     | 0x00  |      |
| Reserved                                                       |                       | 1    | TBD     | [190]     | 0x00  |      |
| Command set revision                                           | CMD_SER_REV           | 1    | R       | [189]     | 0x00  |      |
| Reserved                                                       |                       | 1    | TBD     | [188]     | 0x00  |      |
| Power class                                                    | POWER_CLASS           | 1    | R/W/E_P | [187]     | 0x00  |      |

| Name                                   | Field               | Size | Type                   | CSD-slice | Value | Note |
|----------------------------------------|---------------------|------|------------------------|-----------|-------|------|
| Reserved                               |                     | 1    | TBD                    | [186]     | 0x00  |      |
| High-speed interface timing            | HS_TIMING           | 1    | R/W/E_P                | [185]     | 0x00  |      |
| Strobe Support                         | STROBE_SUPPORT      | 1    | R                      | [184]     | 0x01  |      |
| Bus width mode                         | BUS_WIDTH           | 1    | W/E_P                  | [183]     | 0x00  |      |
| Reserved                               |                     | 1    | TBD                    | [182]     | 0x00  |      |
| Erased memory content                  | ERASED_MENM_CONT    | 1    | R                      | [181]     | 0x00  |      |
| Reserved                               |                     | 1    | TBD                    | [180]     | 0x00  |      |
| Partition configuration                | PARTITION_CONFIG    | 1    | R/W/E & R/W/E_P        | [179]     | 0x00  |      |
| Boot config protection                 | BOOT_CONFIG_PROT    | 1    | R/W & R/W/C_P          | [178]     | 0x00  |      |
| Boot bus Conditions                    | BOOT_BUS_CONDITIONS | 1    | R/W/E                  | [177]     | 0x00  |      |
| Reserved                               |                     | 1    | TBD                    | [176]     | 0x00  |      |
| High-density erase group definition    | ERASE_GROUP_DEF     | 1    | R/W/E_P                | [175]     | 0x00  |      |
| Boot write protection status registers | BOOT_WP_STATUS      | 1    | R                      | [174]     | 0x00  |      |
| Boot area write protection register    | BOOT_WP             | 1    | R/W & R/W/C_P          | [173]     | 0x00  |      |
| Reserved                               |                     | 1    | TBD                    | [172]     | 0x00  |      |
| User area write protection register    | USER_WP             | 1    | R/W, R/W/C_P & R/W/E_P | [171]     | 0x00  |      |
| Reserved                               |                     | 1    | TBD                    | [170]     | 0x00  |      |
| FW configuration                       | FW_CONFIG           | 1    | R/W                    | [169]     | 0x00  |      |
| RPMB Size                              | RPMB_SIZE_MULT      | 1    | R                      | [168]     | 0x20  |      |
| Write reliability setting register     | WR_REL_SET          | 1    | R/W                    | [167]     | 0x1F  |      |
| Write reliability parameter register   | WR_REL_PARAM        | 1    | R                      | [166]     | 0x15  |      |
| Start Sanitize operation               | SANITIZE_START      | 1    | W/E_P                  | [165]     | 0x00  |      |
| Manually start backgroud operations    | BKOPS_START         | 1    | W/E_P                  | [164]     | 0x00  |      |

| Name                                                     | Field                       | Size | Type               | CSD-slice | Value    | Note |
|----------------------------------------------------------|-----------------------------|------|--------------------|-----------|----------|------|
| Enable background operations handshake                   | BKOPS_EN                    | 1    | R/W & R/W/E        | [163]     | 0x00     |      |
| H/W reset function                                       | RST_n_FUNCTION              | 1    | R/W                | [162]     | 0x00     |      |
| HPI management                                           | HPI_MGMT                    | 1    | R/W/E_P            | [161]     | 0x00     |      |
| Partitioning Support                                     | PARTITIONING_SUPPORT        | 1    | R                  | [160]     | 0x07     |      |
| Max Enhanced Area Size                                   | MAX_ENH_SIZE_MULT           | 3    | R                  | [159:157] | 0x0001CE |      |
| Partitions attribute                                     | PARTITIONS_ATTRIBUTE        | 1    | R/W                | [156]     | 0x00     |      |
| Partitioning Setting                                     | PARTITION_SETTING_COMPLETED | 1    | R/W                | [155]     | 0x00     |      |
| General Purpose Partition Size                           | GP_SIZE_MULT                | 12   | R/W                | [154:143] | 0x00     |      |
| Enhanced User Data Area Size                             | ENH_SIZE_MULT               | 3    | R/W                | [142:140] | 0x00     |      |
| Enhanced User Data Start Address                         | ENH_START_ADDR              | 4    | R/W                | [139:136] | 0x00     |      |
| Reserved                                                 |                             | 1    | TBD                | [135]     | 0x00     |      |
| Bad Block Management mode                                | SEC_BAD_BLK_MGMNT           | 1    | R/W                | [134]     | 0x00     |      |
| Production state awareness                               | PRODUCTION_STATE_AWARENESS  | 1    | R/W/E              | [133]     | 0x00     |      |
| Package Case Temperature is controlled                   | TCASE_SUPPORT               | 1    | W/E_P              | [132]     | 0x00     |      |
| Periodic Wake-up                                         | PERIODIC_WAKEUP             | 1    | R/W/E              | [131]     | 0x00     |      |
| Program CID/CSD in DDR mode support                      | PROGRAM_CID_CSD_DDR_SUPPORT | 1    | R                  | [130]     | 0x00     |      |
| Reserved                                                 |                             | 2    | TBD                | [129:128] | 0x00     |      |
| Vendor Specific Fields                                   | VENDOR_SPECIFIC_FIELD       | 64   | vendor or specific | [127:64]  | -        |      |
| Native sector size                                       | USE_NATIVE_SECTOR           | 1    | R                  | [63]      | 0x00     |      |
| Sector size emulation                                    | NATIVE_SECTOR_SIZE          | 1    | R/W                | [62]      | 0x00     |      |
| Sector size                                              | DATA_SECTOR_SIZE            | 1    | R                  | [61]      | 0x00     |      |
| 1st initialization after disabling sector size emulation | INI_TIMEOUT_EMU             | 1    | R                  | [60]      | 0x00     |      |
| Class 6 commands control                                 | CLASS_6_CTRL                | 1    | R/W/E_P            | [59]      | 0x00     |      |
| number of addressed group to be Released                 | DYNCAP_NEEDED               | 1    | R                  | [58]      | 0x00     |      |

| Name                               | Field                              | Size | Type      | CSD-slice | Value      | Note |
|------------------------------------|------------------------------------|------|-----------|-----------|------------|------|
| Exception events control           | EXCEPTION_EVENTS_CTL               | 2    | R/W/E_P   | [57:56]   | 0x00       |      |
| Exception events status            | EXCEPTION_EVENTS_STATUS            | 2    | R         | [55:54]   | 0x00       |      |
| Extended Partitions Attribute      | EXT_PARTITIONS_ATTRIBUTE           | 2    | R/W       | [53:52]   | 0x00       |      |
| Context configuration              | CONTEXT_CONF                       | 15   | R/W/E_P   | [51:37]   | 0x00       |      |
| Packed command status              | PACKED_COMMAND_STATUS              | 1    | R         | [36]      | 0x00       |      |
| Packed command failure index       | PACKED_FAILURE_INDEX               | 1    | R         | [35]      | 0x00       |      |
| Power Off Notification             | POWER_OFF_NOTIFICATION             | 1    | R/W/E_P   | [34]      | 0x00       |      |
| Control to turn the Cache ON/OFF   | CACHE_CTRL                         | 1    | R/W/E_P   | [33]      | 0x00       |      |
| Flushing of the cache              | FLUSH_CACHE                        | 1    | W/E_P     | [32]      | 0x00       |      |
| Control to turn the Barrier ON/OFF | BARRIER_CTRL                       | 1    | R/W       | [31]      | 0x00       |      |
| Mode config                        | MODE_CONFIG                        | 1    | R/W/E_P   | [30]      | 0x00       |      |
| Mode operation codes               | MODE_OPERATION_CODES               | 1    | W/E_P     | [29]      | 0x00       |      |
| Reserved                           |                                    | 2    | TBD       | [28:27]   | 0x00       |      |
| FFU status                         | FFU_STATUS                         | 1    | R         | [26]      | 0x00       |      |
| Pre loading data size              | PRE_LOADING_DATA_SIZE              | 4    | R/W/E_P   | [25:22]   | 0x00       |      |
| Max pre loading data size          | MAX_PRE_LOADING_DATA_SIZE          | 4    | R         | [21:18]   | 0x00738000 |      |
| Product state awareness enablement | PRODUCT_STATE_AWARENESS_ENABLEMENT | 1    | R/W/E & R | [17]      | 0x01       |      |
| Secure Removal Type                | SECURE_REMOVAL_TYPE                | 1    | R/W & R   | [16]      | 0x39       |      |
| Command Queue Mode Enable          | CMDQ_MODE_EN                       | 1    | R/W/E_P   | [15]      | 0x00       |      |
| Reserved                           |                                    | 15   | TBD       | [14:0]    | 0x00       |      |

Note:

1. Register type explanations:

(1) R = Read-only.

(2) R/W = One-time programmable and readable.

(3) R/W/E = Multiple writable with the value kept after a power cycle, assertion of the RST\_n signal, and any CMD0 reset, and readable.

(4) R/W/C\_P = Writable after the value is cleared by a power cycle and assertion of the RST\_n signal (the value not

cleared by CMD0 reset) and readable.

(5) R/W/E\_P = Multiple writable with the value reset after a power cycle, assertion of the RST\_n signal, and any CMD0 reset, and readable.

(6) W/E\_P = Multiple writable with the value reset after power cycle, assertion of the RST\_n signal, and any CMD0 reset, and not readable.

2. Reserved bits should be read as 0.

## 5.5. RCA Register

The writable 16-bit relative card address (RCA) register carries the card address assigned by the host during the card identification. This address is used for the addressed host-card communication after the card identification procedure. The default value of the RCA register is 0x0001. The value 0x0000 is reserved to set all cards into the Stand-by State with CMD7.

# 6. Electrical Characteristics

## 6.1. Supply Voltage

Table 6.1-1. Supply Voltage

| Item | Min  | Max  | Unit |
|------|------|------|------|
| VCCQ | 1.7  | 1.95 | V    |
|      | 2.7  | 3.6  | V    |
| VCC  | 2.7  | 3.6  | V    |
| VSS  | -0.5 | 0.5  | V    |

## 6.2. Bus Signal Line Load

The total capacitance  $C_L$  of each line of the eMMC bus is the sum of the bus master capacitance  $C_{HOST}$ , the bus capacitance  $C_{BUS}$  itself and the capacitance  $C_{DEVICE}$  of the eMMC connected to this line:

$$C_L = C_{HOST} + C_{BUS} + C_{DEVICE}$$

The sum of the host and bus capacitances should be under 20pF.

Table 6.2-1. Bus Signal Line Load

| Parameter                             | Symbol       | Min | Typ. | Max | Unit | Remark                                |
|---------------------------------------|--------------|-----|------|-----|------|---------------------------------------|
| Pull-up resistance for CMD            | $R_{CMD}$    | 4.7 |      | 100 | Kohm | to prevent bus floating               |
| Pull-up resistance for DAT0-DAT7      | $R_{DAT}$    | 10  |      | 100 | Kohm | to prevent bus floating               |
| Internal pull up resistance DAT1-DAT7 | $R_{int}$    | 10  |      | 150 | Kohm | to prevent unconnected lines floating |
| Single Device capacitance             | $C_{DEVICE}$ |     |      | 30  | pF   |                                       |
| Maximum signal line inductance        |              |     |      | 16  | nH   | fPP <= 52 MHz                         |

Table 6.2-2. Capacitance and Resistance for HS400 mode

| Parameter                   | Symbol       | Min | Typ | Max | Unit | Remark        |
|-----------------------------|--------------|-----|-----|-----|------|---------------|
| Bus signal line capacitance | $C_L$        |     |     | 13  | pF   | Single Device |
| Single Device capacitance   | $C_{DEVICE}$ |     |     | 6   | pF   |               |

|                                      |                    |    |  |     |      |  |
|--------------------------------------|--------------------|----|--|-----|------|--|
| Pull-down resistance for Data Strobe | $R_{Data\ Strobe}$ | 10 |  | 100 | Kohm |  |
|--------------------------------------|--------------------|----|--|-----|------|--|

### 6.3. Bus Signal Levels

As the bus can be supplied with a variable supply voltage, all signal levels are related to the supply voltage.

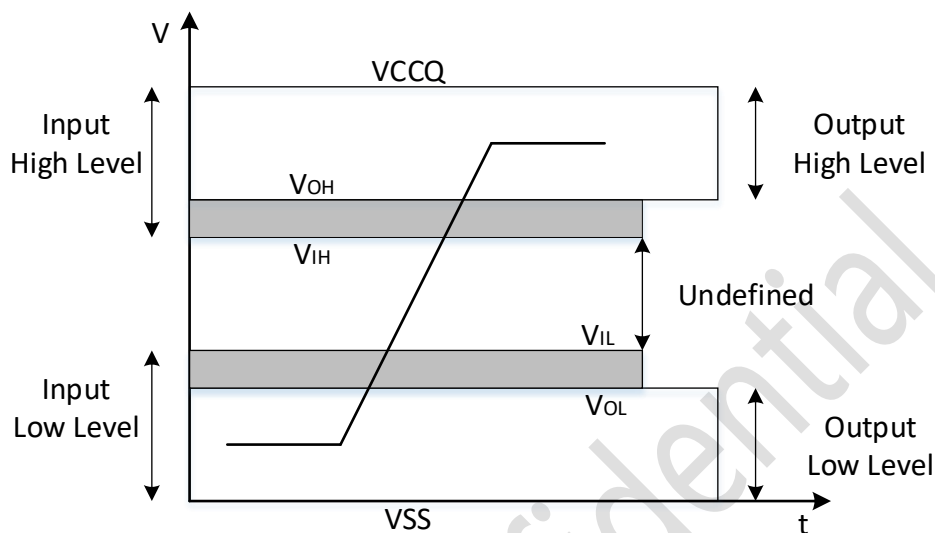


Figure 6.3-1. Bus Signal Levels

Table 6.3-1. Bus Signal Levels

| Parameter                                   | Symbol   | Min               | Max               | Unit | Remark                              |
|---------------------------------------------|----------|-------------------|-------------------|------|-------------------------------------|
| <b>Open-drain mode</b>                      |          |                   |                   |      |                                     |
| Output HIGH voltage                         | $V_{OH}$ | $V_{CCQ} - 0.2$   | -                 | V    | (1)                                 |
| Output LOW voltage                          | $V_{OL}$ | -                 | 0.3               | V    |                                     |
| <b>Push-pull mode (VCCQ: 2.7V - 3.6V)</b>   |          |                   |                   |      |                                     |
| Output HIGH voltage                         | $V_{OH}$ | $0.75 * V_{CCQ}$  | -                 | V    | $I_{OH} = -100\mu A @ V_{CCQ\ min}$ |
| Output LOW voltage                          | $V_{OL}$ | -                 | $0.125 * V_{CCQ}$ | V    | $I_{OL} = 100\mu A @ V_{CCQ\ min}$  |
| Input HIGH voltage                          | $V_{IH}$ | $0.625 * V_{CCQ}$ | $V_{CCQ} + 0.3$   | V    | -                                   |
| Input LOW voltage                           | $V_{IL}$ | $V_{SS} - 0.3$    | $0.25 * V_{CCQ}$  | V    | -                                   |
| <b>Push-pull mode (VCCQ: 1.70V - 1.95V)</b> |          |                   |                   |      |                                     |
| Output HIGH voltage                         | $V_{OH}$ | $V_{CCQ} - 0.45$  | -                 | V    | $I_{OH} = -2mA$                     |
| Output LOW voltage                          | $V_{OL}$ | -                 | 0.45              | V    | $I_{OL} = 2mA$                      |
| Input HIGH voltage                          | $V_{IH}$ | $0.65 * V_{CCQ}$  | $V_{CCQ} + 0.3$   | V    | (2)                                 |
| Input LOW voltage                           | $V_{IL}$ | $V_{SS} - 0.3$    | $0.35 * V_{CCQ}$  | V    | (3)                                 |

#### NOTE:

(1) Because  $V_{OH}$  depends on external resistance value (including outside the package), this value does not apply as device specification. Host is responsible to choose the external pull-up and open drain resistance value to meet  $V_{OH}$  Min value.

(2)  $0.7 * V_{CCQ}$  for MMC4.3 and older revisions.

(3)  $0.3 * V_{CCQ}$  for MMC4.3 and older revisions.

## 6.4. Bus Timing Specification

The Rayson eMMC follows JEDEC standard, for timing specification of all bus mode, including High Speed SDR, High Speed DDR, HS200, HS400, please refer to JESD84-B51 standard.

## 7. Design Guide

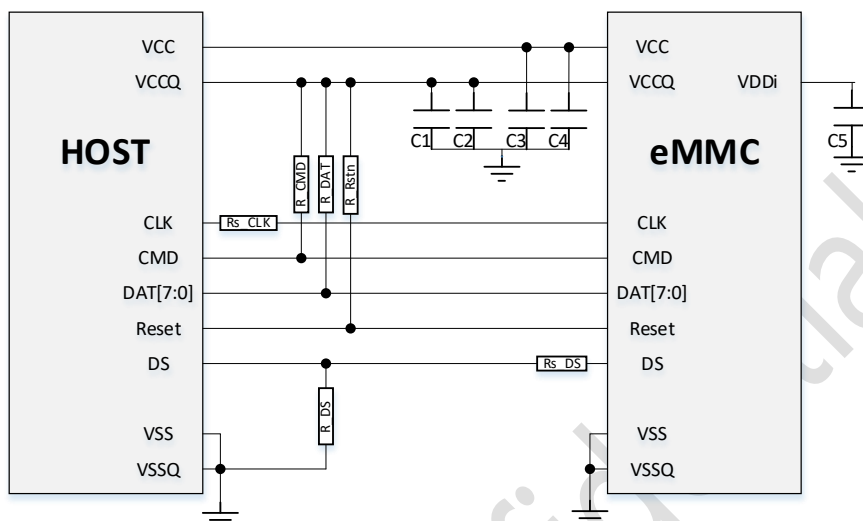


Figure 6.4-1 eMMC Connect Guide

Table 6.4-1. Component recommendation

| Description                   | Symbol | Min. | Max. | Typ. | Unit | Note                                                                                                                                    |
|-------------------------------|--------|------|------|------|------|-----------------------------------------------------------------------------------------------------------------------------------------|
| Pull-up resistance for CMD    | R_CMD  | 4.7  | 100  | 10   | Kohm | Pull-up resistance should be put on CMD line to prevent bus floating.                                                                   |
| Pull-up resistance for DAT0~7 | R_DAT  | 10   | 100  | 50   | Kohm | Pull-up resistance should be put on DAT line to prevent bus floating.                                                                   |
| Data strobe(DS)               | R_DS   | 10   | 100  | 10   | Kohm | Pull-down resistance should be put on DS line to prevent bus floating.                                                                  |
| Serial resistance on DS       | Rs_DS  | 0    | 30   | 0    | ohm  | To reduce overshooting/undershooting<br>Note: If the host uses HS400, we recommend to remove this resistor for better DS signal.        |
| Pull-up resistance for Rstn   | R_Rstn | 10   | 100  | 50   | Kohm | It is not necessary to put pull-up resistance on Rstn line if host does not use H/W reset. (Extended CSD register [162] = 0b)           |
| Serial resistance on CLK      | Rs_CLK | 0    | 30   | 0    | ohm  | To reduce overshooting/undershooting<br>Note: If the host uses HS200/HS400, we recommend to remove this resistor for better CLK signal. |
| VCCQ capacitor value          | C1     | 1    | 10   | 2.2  | uF   | Coupling capacitor should be connected with VCCQ and VSSQ as closely as possible.                                                       |
|                               | C2     | 0.1  | 0.22 | 0.1  | uF   |                                                                                                                                         |
| VCC capacitor value           | C3     | 1    | 10   | 2.2  | uF   | Coupling capacitor should be connected with VCC and VSS as closely as possible.                                                         |
|                               | C4     | 0.1  | 0.22 | 0.1  | uF   |                                                                                                                                         |

| Description                    | Symbol | Min. | Max. | Typ. | Unit | Note                                                                                                              |
|--------------------------------|--------|------|------|------|------|-------------------------------------------------------------------------------------------------------------------|
| VDDi capacitor value           | C5     | 0    | 0.1  | 0    | uF   | No capacitor is recommended.<br>Coupling capacitor should be connected with VDDi and VSSQ as closely as possible. |
| CLK/CMD/DS/DA T[7:0] impedance |        | 45   | 55   | 50   | ohm  | For impedance match.                                                                                              |

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